

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Yuji Okawa
Appl. No. : 10/809,566
Filed : March 25, 2004
For : WAFER BACK SURFACE
TREATING METHOD AND DICING
SHEET ADHERING APPARATUS
Examiner : Thanhha S Pham
Group Art Unit : 2813

AMENDMENT AND RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated September 19, 2006, Applicants submit the following amendments and remarks:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.